

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSP135 H6906	**Issued**	29. August 2013
MA#	MA001091872		
Package	PG-SOT223-4-21	**Weight***	113.52 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.037	0.03		323	
	non noble metal	tin	7440-31-5	0.009	0.01		83	
	inorganic material	silicon	7440-21-3	0.416	0.37	0.41	3661	4067
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		447	
	non noble metal	chromium	7440-47-3	0.152	0.13		1340	
	non noble metal	copper	7440-50-8	50.489	44.48	44.66	444780	446656
wire	non noble metal	copper	7440-50-8	0.020	0.02	0.02	178	178
encapsulation	organic material	carbon black	1333-86-4	0.604	0.53		5317	
	plastics	epoxy resin	-	9.053	7.98		79752	
	inorganic material	silicondioxide	60676-86-0	50.697	44.66	53.17	446614	531683
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12897	12897
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4519	4519
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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